

Application Serial No. 10/785,259  
Reply to office action of June 24, 2005

PATENT  
Docket: CU-3606

**Amendments To The Abstract**

**Clean Version**

The following marked-up version of the amended Abstract is attached hereto to aid the examiner in identifying the changes:

In manufacturing a barrier-forming film, a vapor-deposited inorganic oxide film is provided on a face of a substrate film. An annealing treatment is applied to the substrate film having said vapor-deposited inorganic film. The substrate film is a resinous film which selected from a group consisting of polyesters, polyamides and polypropylenes. The annealing treatment includes a heating treatment carried out at a temperature within the range from 55 °C to 150 °C in order to cause thermal shrinkage of the substrate film and to increase density of the vapor-deposited inorganic oxide film. The vapor-deposited inorganic oxide film includes a vapor-deposited silicon oxide film or a vapor-deposited aluminum oxide film.